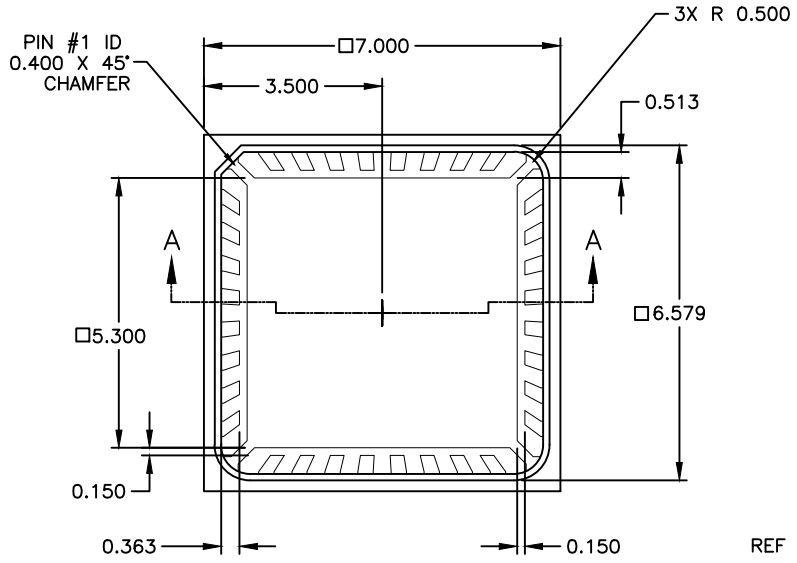
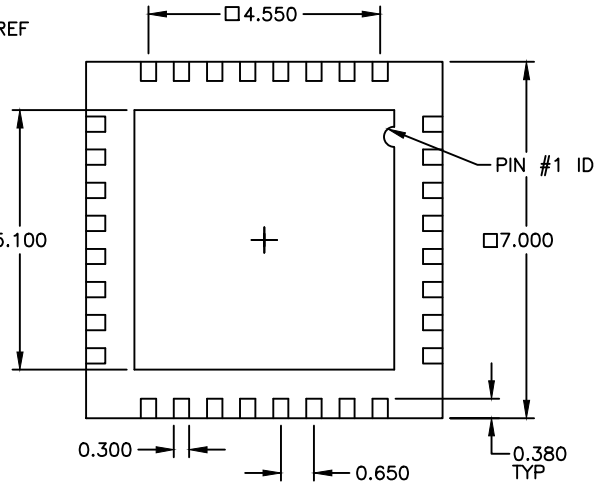
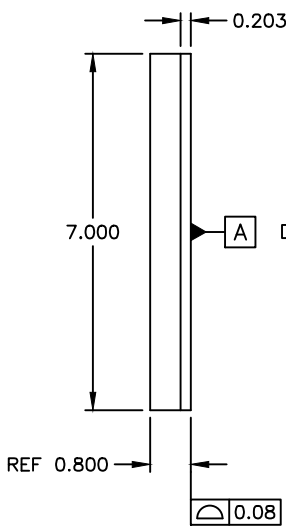


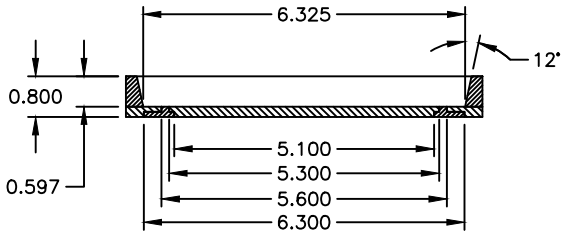
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
		PRODUCTION RELEASE	



TOP VIEW



BOTTOM VIEW



SECTION A-A

NOTES

- MATERIALS:  
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008  
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QUIK-PAK FOR DETAILS.
- FINISH:  
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 100 TO 300 MICRONS (2.5um - 7.6um) THICK.  
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICRONS (1um - 2um) THICK).  
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra).
- PACKAGE MISMATCH: BODY OFFSET TO LEAD FRAME = 0.076mm MAX
- UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.
- PACKAGE CONFORMS TO JEDEC MO-220.

THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETER

TOLERANCES ARE:  
 X.XX ± 0.15    X.XXXX ± ---  
 X.XXX ± 0.050    ANGLES: ± 1°

**DO NOT SCALE DRAWING**

DRAWN BY	CAD DEPT.	DATE	4/5/10
APP BY	STEVE S.	DATE	4/5/10
CUSTOMER	---		
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7mm X 7mm  
 QFN 32 LEAD OmPP

SIZE	PART NO.	REV
A	QP-QFN32-7MM-.65MM	A2
SCALE	CAD FILE	SHEET 1 OF 1
NONE		